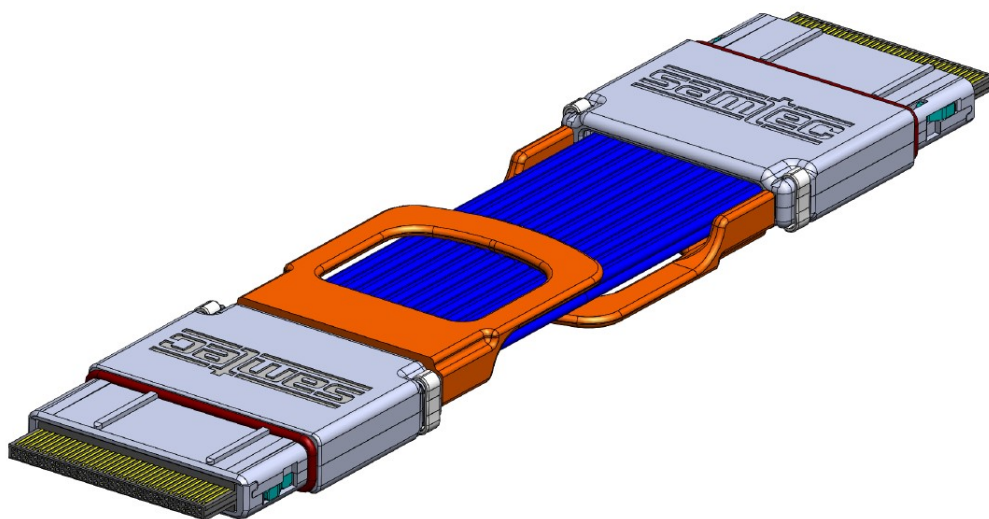


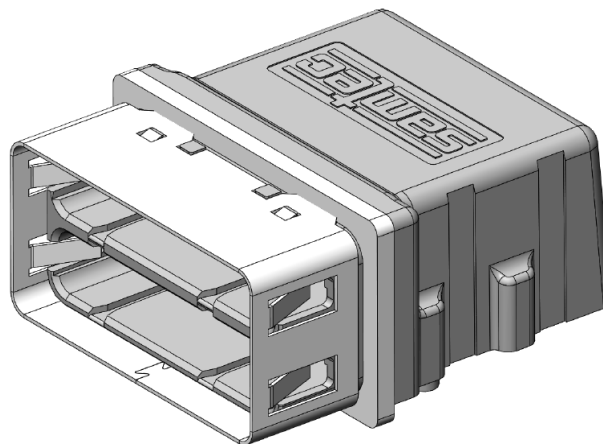
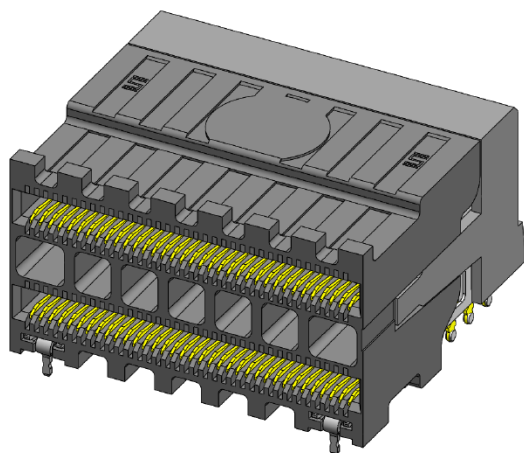
Series: HDLSP 0.635 mm (.025") Eye Speed HD High-Speed High-Density I/O Cable Assembly/ Receptacle

HDLSP Cable Assembly Series



HDI6 Series

HDC Cage



See www.samtec.com for more information.



Series: HDLSP 0.635 mm (.025") Eye Speed HD High-Speed High-Density I/O Cable Assembly/ Receptacle

1.0 SCOPE

- 1.1 This specification covers performance, testing and quality requirements for Samtec HDLSP 0.635 mm (.025") Eye Speed HD High-Speed High-Density I/O Cable Assembly/ Receptacle.

2.0 DETAILED INFORMATION

- 2.1 Product prints, footprints, catalog pages, test reports and other specific, detailed information can be found at HDLSP: <https://www.samtec.com/products/hdlsp>; HDI6: <https://www.samtec.com/products/hdi6>
HDC: <https://www.samtec.com/products/hdc>

3.0 TESTING

- 3.1 **Current Rating:** 1.5A (4 Adjacent Contacts Powered)
3.2 **Voltage Rating:** 150 VAC
3.3 **Operating Temperature Range:** -25°C to +105°C
3.4 **Operating Humidity Range:** up to 95% (Per EIA-364-31)
3.5 **Electrical:**

ITEM	TEST CONDITION	REQUIREMENT
Withstanding Voltage	EIA-364-20 (No Flashover, Sparkover, or Breakdown)	465 VAC
Insulation Resistance	EIA-364-21 (1000 MΩ minimum)	6,000 MΩ
Contact Resistance (LLCR)	EIA-364-23	Δ 15 mΩ (Samtec defined)/ No damage

- 3.6 **Mechanical:**

ITEM	TEST CONDITION	RESULT	STATUS
Durability	EIA-364-09C	100 cycles	PASS
Random Vibration	EIA-364-28 Condition V, Letter B 7.56 G 'RMS', 50 to 2000 Hz, 2 hours per axis, 3 axis total, PSD 0.04 Nanosecond Event Detection: EIA-364-87	Visual Inspection: No Damage LLCR: Δ 15 mΩ No Events	PASS
Mechanical Shock	EIA-364-27 100 G, 6 milliseconds, sawtooth wave, 11.3 fps, 3 shocks/direction, 3 axis (18 total shocks) Nanosecond Event Detection: EIA-364-87	Visual Inspection: No Damage LLCR: Δ 15 mΩ No Events	PASS
Normal Force	EIA-364-04	30 grams minimum for Gold interface	PASS

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3.7 Environmental:

ITEM	TEST CONDITION	RESULT	STATUS
Thermal Shock	EIA-364-32 Thermal Cycles: 100 (30 minute dwell) Hot Temp: +85°C Cold Temp: -55°C Hot/Cold Transition: Immediate	Visual Inspection: No Damage LLCR: Δ 15 m Ω DWV: 465 VAC IR: >6,000 M Ω	PASS
Thermal Aging (Temp Life)	EIA-364-17 Test Condition 4 @ 105°C Condition B for 250 hours	Visual Inspection: No Damage LLCR: Δ 15 m Ω	PASS
Cyclic Humidity	EIA-364-31 Test Temp: 25°C to 65°C Relative Humidity: 90 to 95% Test Duration: 240 hours	Visual Inspection: No Damage LLCR: Δ 15 m Ω DWV: 465 VAC IR: >6,000 M Ω	PASS
Gas Tight	EIA-364-36 Gas Exposure: Nitric Acid Vapor Duration: 60 min. Drying Temp.: 50°C +/- 3°C Measurements: Within 1 hour of Exposure	LLCR: Δ 15 m Ω	PASS

4.0 HIGH SPEED PERFORMANCE

4.1 Empirical Testing – Based on 7dB insertion loss

Assembly	Frequency @ 7dB IL
HDLSP 1.0m length	6.00 GHz
HDLSP 2.0m length	2.50 GHz

Note: The cable assembly bandwidth is based on -7dB insertion loss point of the mated cable assembly. The -7dB point can be used to estimate usable system bandwidth in a typical two-level signaling environment.

4.2 System Impedance: 100 Ohm for differential pair

5.0 APPLICATION PROCEDURE

5.1 Application views

Application view information can be found at link below:

<http://suddendocs.samtec.com/prints/hdlsp-l%20application-mkt.pdf>

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6.0 PROCESSING RECOMMENDATIONS

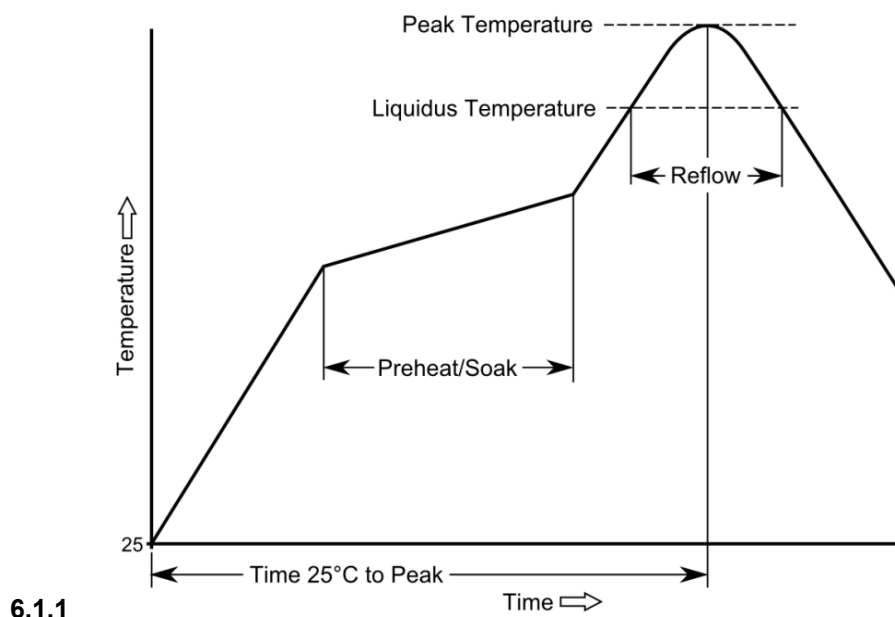
6.1 Due to variances in equipment, solder pastes and applications (board design, component density, etc.), Samtec does not specify a recommended reflow profile for our connectors. The processing parameters provided by the solder paste manufacturer should be employed and can usually be found on their website.

All of Samtec's surface mount components are lead free reflow compatible and compliant with the profile parameters detailed in IPC/JEDEC J-STD-020 which requires that components be capable of withstanding a peak temperature of 260°C as well as 30 seconds above 255°C.

Samtec Recommended Temperature Profile Ranges (SMT)

Pb-Free Assembly

Preheat/Soak (150°C-200°C)	Max Ramp Up Rate	Reflow Time (above 217°C)	Peak Temp	Time within 5°C of 260°C	Max Ramp Down Rate	Time 25°C to Peak Temp
60-120 sec.	3°C/s max.	40-150 sec.	260°C	30 sec. max.	6°C/s max.	8 min. max.



These guidelines should not be considered design requirements for all applications. Samtec recommends testing interconnects on your boards in your process to guarantee optimum results.

6.2 Maximum Reflow Passes: The parts can withstand three reflow passes at a maximum component temperature of 260°C.

6.3 Stencil Thickness: The stencil thickness is .006" (0,15 mm).

6.4 Placement: Machine placement of the parts is recommended.

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6.5 Reflow Environment: Samtec recommends the use of a low level oxygen environment (typically achieved through Nitrogen gas infusion) in the reflow process to improve solderability.

6.6 Inverted Reflow: For applications requiring inverted reflow soldering, use of an epoxy adhesive is recommended. For more information on the use of epoxy adhesives, please visit the Processing page on our website or contact Samtec's Interconnect Processing Group at IPG@samtec.com.

6.7 Handling:

- 6.7.1** These connectors are typically packaged in trays or tape-and-reel which protect the solder crimps from damage. They should be handled like any other BGA or IC device.
- 6.7.2** Avoid resting the connector on the solder crimps except during final placement onto the board.
- 6.7.3** When using tape-and-reel packaging, ensure the bottom of the pocket is protected as it travels through the feeder.
- 6.7.4** Avoid touching the solder crimps.
- 6.7.5** When a partially used tray needs to be stored, use the flat cover from the original shipment or an empty tray to cover connectors. Band trays using flex wrap or rubber bands.

6.8 Cleaning: Samtec, Inc. has verified that our connectors may be cleaned in accordance with the solvents and conditions designated in the EIA-364-11 standard.

7.0 ADDITIONAL RESOURCES

- 7.1** For additional mechanical testing or product information, contact our Customer Engineering Support Group at CES@samtec.com
- 7.2** For additional information on high speed performance testing, contact our Signal Integrity Group at SIG@samtec.com
- 7.3** For additional processing information, contact our Interconnect Processing Group at IPG@samtec.com.
- 7.4** For RoHS, REACH or other environmental compliance information, contact our Product Environmental Compliance Group at PEC@samtec.com

USE OF PRODUCT SPECIFICATION SHEET

This Product Specification Sheet ("PSS") is a brief summary of information related to the Product identified. As a summary, it should only be used for the limited purpose of considering the purchase/use of Product. For specific, detailed information, including but not limited to testing and Product footprint, refer to Section 2.0 of this document and the links there provided to test reports and prints. This PSS is the property of Samtec, Inc. ("Samtec") and contains proprietary information of Samtec, our various licensors, or both. Samtec does not grant express or implied rights or license under any patent, copyright, trademark or other proprietary rights and the use of the PSS for building, reverse engineering or replication is strictly prohibited. By using the PSS, the user agrees to not infringe, directly or indirectly, upon any intellectual property rights of Samtec and acknowledges that Samtec, our various licensors, or both own all intellectual property therein. The PSS is presented "AS IS". While Samtec makes every effort to present excellent information, the PSS is only provided as a guideline and does not, therefore, warrant it is without error or defect or that the PSS contains all necessary and/or relevant information about the Product. The user agrees that all access and use of the PSS is at its own risk. **NO WARRANTIES EXPRESSED OR IMPLIED, INCLUDING ANY WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR OF ANY KIND WHATSOEVER ARE PROVIDED.**